

L Number	Hits	Search Text	DB	Time stamp
1	95116	((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet)))	USPAT; US-PGPUB	2003/10/03 20:27
2	41998	((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3	USPAT; US-PGPUB	2003/10/03 20:27
3	29778	((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric))	USPAT; US-PGPUB	2003/10/03 20:28
4	19779	((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and etch\$3	USPAT; US-PGPUB	2003/10/03 20:03
5	17404	(((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and etch\$3) and (trench recess open\$3 hole groove)	USPAT; US-PGPUB	2003/10/03 20:28
6	16468	(((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and etch\$3) and (trench recess open\$3 hole groove)) and (semiconductor wafer substrate)	USPAT; US-PGPUB	2003/10/03 20:04
7	16445	(((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and etch\$3) and (trench recess open\$3 hole groove)) and (semiconductor wafer substrate)) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel)))	USPAT; US-PGPUB	2003/10/03 20:14
8	11101	(((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and etch\$3) and (trench recess open\$3 hole groove)) and (semiconductor wafer substrate)) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel)))) and (PR photoresist resist photo?resist)	USPAT; US-PGPUB	2003/10/03 20:07
9	5001	(((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and etch\$3) and (trench recess open\$3 hole groove)) and (semiconductor wafer substrate)) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel)))) and (PR photoresist resist photo?resist)) and resin	USPAT; US-PGPUB	2003/10/03 20:28
10	147	(((((((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and etch\$3) and (trench recess open\$3 hole groove)) and (semiconductor wafer substrate)) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel)))) and (PR photoresist resist photo?resist)) and resin) and (electroless near3 plat\$3) electro?plat\$3 (electro near3 plat\$3))	USPAT; US-PGPUB	2003/10/03 20:14
11	13409	conduct\$3 near5 foil	USPAT; US-PGPUB	2003/10/03 20:13
12	10122	(conduct\$3 near5 foil) and (trench recess open\$3 hole groove)	USPAT; US-PGPUB	2003/10/03 20:14
13	9566	((conduct\$3 near5 foil) and (trench recess open\$3 hole groove)) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel)))	USPAT; US-PGPUB	2003/10/03 20:14
14	142	((conduct\$3 near5 foil) and (trench recess open\$3 hole groove)) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel)))) and (electroless near3 plat\$3) electro?plat\$3 (electro near3 plat\$3))	USPAT; US-PGPUB	2003/10/03 20:15
15	6911	conductive near3 foil	USPAT; US-PGPUB	2003/10/03 20:16
16	31	(conductive near3 foil) and (isolat\$3 near5 trench)	USPAT; US-PGPUB	2003/10/03 20:16
17	65334	(conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet)))	EPO; JPO; DERWENT; IBM TDB	2003/10/03 20:27

18	8676	((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3	EPO; JPO; DERWENT; IBM_TDB	2003/10/03 20:28
19	3516	((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric))	EPO; JPO; DERWENT; IBM_TDB	2003/10/03 20:28
20	1446	(((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and (trench recess open\$3 hole groove))	EPO; JPO; DERWENT; IBM_TDB	2003/10/03 20:28
21	271	(((((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric)) and (trench recess open\$3 hole groove)) and resin	EPO; JPO; DERWENT; IBM_TDB	2003/10/03 20:29